

Global Molding Equipment for Wafer and Panel Level Packaging Market Growth 2026-2032

<https://marketpublishers.com/r/GE37AC981205EN.html>

Date: June 2026

Pages: 102

Price: US\$ 3,660.00 (Single User License)

ID: GE37AC981205EN

Abstracts

The global Molding Equipment for Wafer and Panel Level Packaging market size is predicted to grow from US\$ 397 million in 2025 to US\$ 651 million in 2032; it is expected to grow at a CAGR of 7.5% from 2026 to 2032.

In 2024, global Molding Equipment for Wafer and Panel Level Packaging production reached approximately 387 units, with an average global market price of around US\$ 974,250 per unit.

Molding Equipment for Wafer and Panel Level Packaging is core semiconductor advanced packaging equipment used for encapsulating wafers or large-size panels. It applies molding compounds (epoxy resins, etc.) to the surface of wafers/panels through precision molding processes such as transfer molding or compression molding, forming a uniform protective layer that integrates multiple chips. Featuring high molding precision, excellent encapsulation uniformity, and compatibility with large-size substrates, it effectively protects chips from environmental interference, enhances mechanical stability and electrical performance, and is critical for realizing heterogeneous integration and 3D stacking in advanced packaging technologies (e.g., fan-out wafer/panel level packaging).

The single-line production capacity of Molding Equipment for Wafer and Panel Level Packaging is 39 to 42 units per year, the average gross profit margin was 45.2%.

The cost structure of Molding Equipment for Wafer and Panel Level Packaging is dominated by four core components with clear weights: core component costs account for the largest share at 45%-55%, mainly including precision molding modules, high-precision motion control systems, temperature/pressure control units, and die-casting

mechanisms, where the accuracy and stability of core components directly determine the equipment's process capability and cost level. R&D and certification costs make up 25%-30%, dedicated to optimizing molding process parameters, improving compatibility with large-size panels and special molding compounds, and meeting SEMI semiconductor industry standards, as high technological barriers and strict reliability verification are key to market entry. Production and assembly costs represent 15%-20%, covering precision machining, system integration, and long-term stability testing?high-precision assembly and process calibration for large-size substrates increase manufacturing complexity. Packaging and logistics costs constitute the remaining 5%-8%, including shockproof packaging, professional transportation, and on-site installation and commissioning services, with high requirements for equipment transportation safety and technical support.

The industry chain of Molding Equipment for Wafer and Panel Level Packaging consists of three interconnected tiers: upstream includes suppliers of core components (motion control systems, precision molds, temperature/pressure sensors), raw materials (epoxy molding compounds), precision mechanical parts, and electronic components, as well as providers of process software and testing instruments. Midstream involves enterprises engaged in product design, core component integration, system assembly, and performance calibration, focusing on adjusting equipment specifications and process parameters to adapt to different wafer/panel sizes and advanced packaging process requirements (e.g., 3D stacking, heterogeneous integration). Downstream covers semiconductor wafer fabs, advanced packaging and testing enterprises (OSAT), and IDM manufacturers, with demand driven by the upgrading of semiconductor advanced packaging technologies and the expansion of applications in high-performance computing, AI, and automotive electronics.

Demand for Molding Equipment for Wafer and Panel Level Packaging is growing rapidly driven by the global expansion of advanced packaging markets, the widespread adoption of wafer/panel level packaging technologies, and the surge in demand for high-performance chips in AI, 5G, and intelligent driving. It addresses pain points such as low efficiency and poor uniformity of traditional packaging equipment in large-size substrate processing, while the accelerated domestic substitution trend in semiconductor equipment provides broad market space. Key business opportunities lie in developing high-precision equipment for large-size panel level packaging to meet mass production needs, optimizing compatibility with third-generation semiconductor materials and new molding compounds, and expanding into emerging semiconductor manufacturing hubs. Additionally, strengthening independent R&D of core technologies to break foreign monopolies and collaborating with downstream enterprises for customized process

solutions can further tap into the high-growth potential of the advanced packaging equipment market.

LP Information, Inc. (LPI) ' newest research report, the "Molding Equipment for Wafer and Panel Level Packaging Industry Forecast" looks at past sales and reviews total world Molding Equipment for Wafer and Panel Level Packaging sales in 2025, providing a comprehensive analysis by region and market sector of projected Molding Equipment for Wafer and Panel Level Packaging sales for 2026 through 2032. With Molding Equipment for Wafer and Panel Level Packaging sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US\$ millions of the world Molding Equipment for Wafer and Panel Level Packaging industry.

This Insight Report provides a comprehensive analysis of the global Molding Equipment for Wafer and Panel Level Packaging landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on Molding Equipment for Wafer and Panel Level Packaging portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Molding Equipment for Wafer and Panel Level Packaging market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Molding Equipment for Wafer and Panel Level Packaging and breaks down the forecast by Molding Method, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Molding Equipment for Wafer and Panel Level Packaging.

This report presents a comprehensive overview, market shares, and growth opportunities of Molding Equipment for Wafer and Panel Level Packaging market by product type, application, key manufacturers and key regions and countries.

Segmentation by Molding Method:

Compression Molding

Transfer Molding

Injection Molding

Vacuum-Assisted Molding

Segmentation by Substrate Format:

Wafer-Level Molding (200 Mm / 300 Mm)

Panel-Level Molding (Large Panel / Fan-Out Panel)

Strip-Level Molding

Segmentation by Automation Level:

Semi-Automatic Molding System

Fully Automatic Molding System

Segmentation by Application:

Semiconductor Packaging

Advanced Packaging For Mobile And Consumer Electronics

Automotive And Industrial Electronics

High-Reliability And IoT Devices

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

APAC

China

Japan

Korea

Southeast Asia

India

Australia

Europe

Germany

France

UK

Italy

Russia

Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

Towa

Besi

ASMPT

APIC YAMADA (Yamaha Robotics)

Shanghai Xinsheng

Tongling Trinity Technology

I-PEX

Kitakami Techno

Key Questions Addressed in this Report

What is the 10-year outlook for the global Molding Equipment for Wafer and Panel Level Packaging market?

What factors are driving Molding Equipment for Wafer and Panel Level Packaging market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do Molding Equipment for Wafer and Panel Level Packaging market opportunities vary by end market size?

How does Molding Equipment for Wafer and Panel Level Packaging break out by Molding Method, by Application?

Contents

1 SCOPE OF THE REPORT

- 1.1 Market Introduction
- 1.2 Years Considered
- 1.3 Research Objectives
- 1.4 Market Research Methodology
- 1.5 Research Process and Data Source
- 1.6 Economic Indicators
- 1.7 Currency Considered
- 1.8 Market Estimation Caveats

2 EXECUTIVE SUMMARY

2.1 World Market Overview

2.1.1 Global Molding Equipment for Wafer and Panel Level Packaging Annual Sales 2021-2032

2.1.2 World Current & Future Analysis for Molding Equipment for Wafer and Panel Level Packaging by Geographic Region, 2021, 2025 & 2032

2.1.3 World Current & Future Analysis for Molding Equipment for Wafer and Panel Level Packaging by Country/Region, 2021, 2025 & 2032

2.2 Molding Equipment for Wafer and Panel Level Packaging Segment by Molding Method

2.2.1 Compression Molding

2.2.2 Transfer Molding

2.2.3 Injection Molding

2.2.4 Vacuum-Assisted Molding

2.2.5 Molding Equipment for Wafer and Panel Level Packaging Sales by Molding Method

2.2.5.1 Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Molding Method (2021-2026)

2.2.5.2 Global Molding Equipment for Wafer and Panel Level Packaging Revenue and Market Share by Molding Method (2021-2026)

2.2.5.3 Global Molding Equipment for Wafer and Panel Level Packaging Sale Price by Molding Method (2021-2026)

2.3 Molding Equipment for Wafer and Panel Level Packaging Segment by Substrate Format

2.3.1 Wafer-Level Molding (200 Mm / 300 Mm)

2.3.2 Panel-Level Molding (Large Panel / Fan-Out Panel)

2.3.3 Strip-Level Molding

2.3.4 Molding Equipment for Wafer and Panel Level Packaging Sales by Substrate Format

2.3.4.1 Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Substrate Format (2021-2026)

2.3.4.2 Global Molding Equipment for Wafer and Panel Level Packaging Revenue and Market Share by Substrate Format (2021-2026)

2.3.4.3 Global Molding Equipment for Wafer and Panel Level Packaging Sale Price by Substrate Format (2021-2026)

2.4 Molding Equipment for Wafer and Panel Level Packaging Segment by Automation Level

2.4.1 Semi-Automatic Molding System

2.4.2 Fully Automatic Molding System

2.4.3 Molding Equipment for Wafer and Panel Level Packaging Sales by Automation Level

2.4.3.1 Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Automation Level (2021-2026)

2.4.3.2 Global Molding Equipment for Wafer and Panel Level Packaging Revenue and Market Share by Automation Level (2021-2026)

2.4.3.3 Global Molding Equipment for Wafer and Panel Level Packaging Sale Price by Automation Level (2021-2026)

2.5 Molding Equipment for Wafer and Panel Level Packaging Segment by Application

2.5.1 Semiconductor Packaging

2.5.2 Advanced Packaging For Mobile And Consumer Electronics

2.5.3 Automotive And Industrial Electronics

2.5.4 High-Reliability And IoT Devices

2.5.5 Molding Equipment for Wafer and Panel Level Packaging Sales by Application

2.5.5.1 Global Molding Equipment for Wafer and Panel Level Packaging Sale Market Share by Application (2021-2026)

2.5.5.2 Global Molding Equipment for Wafer and Panel Level Packaging Revenue and Market Share by Application (2021-2026)

2.5.5.3 Global Molding Equipment for Wafer and Panel Level Packaging Sale Price by Application (2021-2026)

3 GLOBAL BY COMPANY

3.1 Global Molding Equipment for Wafer and Panel Level Packaging Breakdown Data by Company

3.1.1 Global Molding Equipment for Wafer and Panel Level Packaging Annual Sales by Company (2021-2026)

3.1.2 Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Company (2021-2026)

3.2 Global Molding Equipment for Wafer and Panel Level Packaging Annual Revenue by Company (2021-2026)

3.2.1 Global Molding Equipment for Wafer and Panel Level Packaging Revenue by Company (2021-2026)

3.2.2 Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Company (2021-2026)

3.3 Global Molding Equipment for Wafer and Panel Level Packaging Sale Price by Company

3.4 Key Manufacturers Molding Equipment for Wafer and Panel Level Packaging Producing Area Distribution, Sales Area, Product Type

3.4.1 Key Manufacturers Molding Equipment for Wafer and Panel Level Packaging Product Location Distribution

3.4.2 Players Molding Equipment for Wafer and Panel Level Packaging Products Offered

3.5 Market Concentration Rate Analysis

3.5.1 Competition Landscape Analysis

3.5.2 Concentration Ratio (CR3, CR5 and CR10) & (2024-2026)

3.6 New Products and Potential Entrants

3.7 Market M&A Activity & Strategy

4 WORLD HISTORIC REVIEW FOR MOLDING EQUIPMENT FOR WAFER AND PANEL LEVEL PACKAGING BY GEOGRAPHIC REGION

4.1 World Historic Molding Equipment for Wafer and Panel Level Packaging Market Size by Geographic Region (2021-2026)

4.1.1 Global Molding Equipment for Wafer and Panel Level Packaging Annual Sales by Geographic Region (2021-2026)

4.1.2 Global Molding Equipment for Wafer and Panel Level Packaging Annual Revenue by Geographic Region (2021-2026)

4.2 World Historic Molding Equipment for Wafer and Panel Level Packaging Market Size by Country/Region (2021-2026)

4.2.1 Global Molding Equipment for Wafer and Panel Level Packaging Annual Sales by Country/Region (2021-2026)

4.2.2 Global Molding Equipment for Wafer and Panel Level Packaging Annual Revenue by Country/Region (2021-2026)

- 4.3 Americas Molding Equipment for Wafer and Panel Level Packaging Sales Growth
- 4.4 APAC Molding Equipment for Wafer and Panel Level Packaging Sales Growth
- 4.5 Europe Molding Equipment for Wafer and Panel Level Packaging Sales Growth
- 4.6 Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales Growth

5 AMERICAS

5.1 Americas Molding Equipment for Wafer and Panel Level Packaging Sales by Country

5.1.1 Americas Molding Equipment for Wafer and Panel Level Packaging Sales by Country (2021-2026)

5.1.2 Americas Molding Equipment for Wafer and Panel Level Packaging Revenue by Country (2021-2026)

5.2 Americas Molding Equipment for Wafer and Panel Level Packaging Sales by Molding Method (2021-2026)

5.3 Americas Molding Equipment for Wafer and Panel Level Packaging Sales by Application (2021-2026)

5.4 United States

5.5 Canada

5.6 Mexico

5.7 Brazil

6 APAC

6.1 APAC Molding Equipment for Wafer and Panel Level Packaging Sales by Region

6.1.1 APAC Molding Equipment for Wafer and Panel Level Packaging Sales by Region (2021-2026)

6.1.2 APAC Molding Equipment for Wafer and Panel Level Packaging Revenue by Region (2021-2026)

6.2 APAC Molding Equipment for Wafer and Panel Level Packaging Sales by Molding Method (2021-2026)

6.3 APAC Molding Equipment for Wafer and Panel Level Packaging Sales by Application (2021-2026)

6.4 China

6.5 Japan

6.6 South Korea

6.7 Southeast Asia

6.8 India

6.9 Australia

6.10 China Taiwan

7 EUROPE

7.1 Europe Molding Equipment for Wafer and Panel Level Packaging by Country

7.1.1 Europe Molding Equipment for Wafer and Panel Level Packaging Sales by Country (2021-2026)

7.1.2 Europe Molding Equipment for Wafer and Panel Level Packaging Revenue by Country (2021-2026)

7.2 Europe Molding Equipment for Wafer and Panel Level Packaging Sales by Molding Method (2021-2026)

7.3 Europe Molding Equipment for Wafer and Panel Level Packaging Sales by Application (2021-2026)

7.4 Germany

7.5 France

7.6 UK

7.7 Italy

7.8 Russia

8 MIDDLE EAST & AFRICA

8.1 Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging by Country

8.1.1 Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales by Country (2021-2026)

8.1.2 Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Revenue by Country (2021-2026)

8.2 Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales by Molding Method (2021-2026)

8.3 Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales by Application (2021-2026)

8.4 Egypt

8.5 South Africa

8.6 Israel

8.7 Turkey

8.8 GCC Countries

9 MARKET DRIVERS, CHALLENGES AND TRENDS

- 9.1 Market Drivers & Growth Opportunities
- 9.2 Market Challenges & Risks
- 9.3 Industry Trends

10 MANUFACTURING COST STRUCTURE ANALYSIS

- 10.1 Raw Material and Suppliers
- 10.2 Manufacturing Cost Structure Analysis of Molding Equipment for Wafer and Panel Level Packaging
- 10.3 Manufacturing Process Analysis of Molding Equipment for Wafer and Panel Level Packaging
- 10.4 Industry Chain Structure of Molding Equipment for Wafer and Panel Level Packaging

11 MARKETING, DISTRIBUTORS AND CUSTOMER

- 11.1 Sales Channel
 - 11.1.1 Direct Channels
 - 11.1.2 Indirect Channels
- 11.2 Molding Equipment for Wafer and Panel Level Packaging Distributors
- 11.3 Molding Equipment for Wafer and Panel Level Packaging Customer

12 WORLD FORECAST REVIEW FOR MOLDING EQUIPMENT FOR WAFER AND PANEL LEVEL PACKAGING BY GEOGRAPHIC REGION

- 12.1 Global Molding Equipment for Wafer and Panel Level Packaging Market Size Forecast by Region
 - 12.1.1 Global Molding Equipment for Wafer and Panel Level Packaging Forecast by Region (2027-2032)
 - 12.1.2 Global Molding Equipment for Wafer and Panel Level Packaging Annual Revenue Forecast by Region (2027-2032)
- 12.2 Americas Forecast by Country (2027-2032)
- 12.3 APAC Forecast by Region (2027-2032)
- 12.4 Europe Forecast by Country (2027-2032)
- 12.5 Middle East & Africa Forecast by Country (2027-2032)
- 12.6 Global Molding Equipment for Wafer and Panel Level Packaging Forecast by Molding Method (2027-2032)
- 12.7 Global Molding Equipment for Wafer and Panel Level Packaging Forecast by

Application (2027-2032)

13 KEY PLAYERS ANALYSIS

13.1 Towa

13.1.1 Towa Company Information

13.1.2 Towa Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

13.1.3 Towa Molding Equipment for Wafer and Panel Level Packaging Sales, Revenue, Price and Gross Margin (2021-2026)

13.1.4 Towa Main Business Overview

13.1.5 Towa Latest Developments

13.2 Besi

13.2.1 Besi Company Information

13.2.2 Besi Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

13.2.3 Besi Molding Equipment for Wafer and Panel Level Packaging Sales, Revenue, Price and Gross Margin (2021-2026)

13.2.4 Besi Main Business Overview

13.2.5 Besi Latest Developments

13.3 ASMPT

13.3.1 ASMPT Company Information

13.3.2 ASMPT Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

13.3.3 ASMPT Molding Equipment for Wafer and Panel Level Packaging Sales, Revenue, Price and Gross Margin (2021-2026)

13.3.4 ASMPT Main Business Overview

13.3.5 ASMPT Latest Developments

13.4 APIC YAMADA (Yamaha Robotics)

13.4.1 APIC YAMADA (Yamaha Robotics) Company Information

13.4.2 APIC YAMADA (Yamaha Robotics) Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

13.4.3 APIC YAMADA (Yamaha Robotics) Molding Equipment for Wafer and Panel Level Packaging Sales, Revenue, Price and Gross Margin (2021-2026)

13.4.4 APIC YAMADA (Yamaha Robotics) Main Business Overview

13.4.5 APIC YAMADA (Yamaha Robotics) Latest Developments

13.5 Shanghai Xinsheng

13.5.1 Shanghai Xinsheng Company Information

13.5.2 Shanghai Xinsheng Molding Equipment for Wafer and Panel Level Packaging

Product Portfolios and Specifications

13.5.3 Shanghai Xinsheng Molding Equipment for Wafer and Panel Level Packaging Sales, Revenue, Price and Gross Margin (2021-2026)

13.5.4 Shanghai Xinsheng Main Business Overview

13.5.5 Shanghai Xinsheng Latest Developments

13.6 Tongling Trinity Technology

13.6.1 Tongling Trinity Technology Company Information

13.6.2 Tongling Trinity Technology Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

13.6.3 Tongling Trinity Technology Molding Equipment for Wafer and Panel Level Packaging Sales, Revenue, Price and Gross Margin (2021-2026)

13.6.4 Tongling Trinity Technology Main Business Overview

13.6.5 Tongling Trinity Technology Latest Developments

13.7 I-PEX

13.7.1 I-PEX Company Information

13.7.2 I-PEX Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

13.7.3 I-PEX Molding Equipment for Wafer and Panel Level Packaging Sales, Revenue, Price and Gross Margin (2021-2026)

13.7.4 I-PEX Main Business Overview

13.7.5 I-PEX Latest Developments

13.8 Kitakami Techno

13.8.1 Kitakami Techno Company Information

13.8.2 Kitakami Techno Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

13.8.3 Kitakami Techno Molding Equipment for Wafer and Panel Level Packaging Sales, Revenue, Price and Gross Margin (2021-2026)

13.8.4 Kitakami Techno Main Business Overview

13.8.5 Kitakami Techno Latest Developments

14 RESEARCH FINDINGS AND CONCLUSION

List Of Tables

LIST OF TABLES

Table 1. Molding Equipment for Wafer and Panel Level Packaging Annual Sales CAGR by Geographic Region (2021, 2025 & 2032) & (\$ millions)

Table 2. Molding Equipment for Wafer and Panel Level Packaging Annual Sales CAGR by Country/Region (2021, 2025 & 2032) & (\$ millions)

Table 3. Major Players of Compression Molding

Table 4. Major Players of Transfer Molding

Table 5. Major Players of Injection Molding

Table 6. Major Players of Vacuum-Assisted Molding

Table 7. Global Molding Equipment for Wafer and Panel Level Packaging Sales by Molding Method (2021-2026) & (Units)

Table 8. Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Molding Method (2021-2026)

Table 9. Global Molding Equipment for Wafer and Panel Level Packaging Revenue by Molding Method (2021-2026) & (\$ million)

Table 10. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Molding Method (2021-2026)

Table 11. Global Molding Equipment for Wafer and Panel Level Packaging Sale Price by Molding Method (2021-2026) & (US\$/Unit)

Table 12. Major Players of Wafer-Level Molding (200 Mm / 300 Mm)

Table 13. Major Players of Panel-Level Molding (Large Panel / Fan-Out Panel)

Table 14. Major Players of Strip-Level Molding

Table 15. Global Molding Equipment for Wafer and Panel Level Packaging Sales by Substrate Format (2021-2026) & (Units)

Table 16. Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Substrate Format (2021-2026)

Table 17. Global Molding Equipment for Wafer and Panel Level Packaging Revenue by Substrate Format (2021-2026) & (\$ million)

Table 18. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Substrate Format (2021-2026)

Table 19. Global Molding Equipment for Wafer and Panel Level Packaging Sale Price by Substrate Format (2021-2026) & (US\$/Unit)

Table 20. Major Players of Semi-Automatic Molding System

Table 21. Major Players of Fully Automatic Molding System

Table 22. Global Molding Equipment for Wafer and Panel Level Packaging Sales by Automation Level (2021-2026) & (Units)

Table 23. Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Automation Level (2021-2026)

Table 24. Global Molding Equipment for Wafer and Panel Level Packaging Revenue by Automation Level (2021-2026) & (\$ million)

Table 25. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Automation Level (2021-2026)

Table 26. Global Molding Equipment for Wafer and Panel Level Packaging Sale Price by Automation Level (2021-2026) & (US\$/Unit)

Table 27. Global Molding Equipment for Wafer and Panel Level Packaging Sale by Application (2021-2026) & (Units)

Table 28. Global Molding Equipment for Wafer and Panel Level Packaging Sale Market Share by Application (2021-2026)

Table 29. Global Molding Equipment for Wafer and Panel Level Packaging Revenue by Application (2021-2026) & (\$ million)

Table 30. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Application (2021-2026)

Table 31. Global Molding Equipment for Wafer and Panel Level Packaging Sale Price by Application (2021-2026) & (US\$/Unit)

Table 32. Global Molding Equipment for Wafer and Panel Level Packaging Sales by Company (2021-2026) & (Units)

Table 33. Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Company (2021-2026)

Table 34. Global Molding Equipment for Wafer and Panel Level Packaging Revenue by Company (2021-2026) & (\$ millions)

Table 35. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Company (2021-2026)

Table 36. Global Molding Equipment for Wafer and Panel Level Packaging Sale Price by Company (2021-2026) & (US\$/Unit)

Table 37. Key Manufacturers Molding Equipment for Wafer and Panel Level Packaging Producing Area Distribution and Sales Area

Table 38. Players Molding Equipment for Wafer and Panel Level Packaging Products Offered

Table 39. Molding Equipment for Wafer and Panel Level Packaging Concentration Ratio (CR3, CR5 and CR10) & (2024-2026)

Table 40. New Products and Potential Entrants

Table 41. Market M&A Activity & Strategy

Table 42. Global Molding Equipment for Wafer and Panel Level Packaging Sales by Geographic Region (2021-2026) & (Units)

Table 43. Global Molding Equipment for Wafer and Panel Level Packaging Sales

Market Share Geographic Region (2021-2026)

Table 44. Global Molding Equipment for Wafer and Panel Level Packaging Revenue by Geographic Region (2021-2026) & (\$ millions)

Table 45. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Geographic Region (2021-2026)

Table 46. Global Molding Equipment for Wafer and Panel Level Packaging Sales by Country/Region (2021-2026) & (Units)

Table 47. Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Country/Region (2021-2026)

Table 48. Global Molding Equipment for Wafer and Panel Level Packaging Revenue by Country/Region (2021-2026) & (\$ millions)

Table 49. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Country/Region (2021-2026)

Table 50. Americas Molding Equipment for Wafer and Panel Level Packaging Sales by Country (2021-2026) & (Units)

Table 51. Americas Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Country (2021-2026)

Table 52. Americas Molding Equipment for Wafer and Panel Level Packaging Revenue by Country (2021-2026) & (\$ millions)

Table 53. Americas Molding Equipment for Wafer and Panel Level Packaging Sales by Molding Method (2021-2026) & (Units)

Table 54. Americas Molding Equipment for Wafer and Panel Level Packaging Sales by Application (2021-2026) & (Units)

Table 55. APAC Molding Equipment for Wafer and Panel Level Packaging Sales by Region (2021-2026) & (Units)

Table 56. APAC Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Region (2021-2026)

Table 57. APAC Molding Equipment for Wafer and Panel Level Packaging Revenue by Region (2021-2026) & (\$ millions)

Table 58. APAC Molding Equipment for Wafer and Panel Level Packaging Sales by Molding Method (2021-2026) & (Units)

Table 59. APAC Molding Equipment for Wafer and Panel Level Packaging Sales by Application (2021-2026) & (Units)

Table 60. Europe Molding Equipment for Wafer and Panel Level Packaging Sales by Country (2021-2026) & (Units)

Table 61. Europe Molding Equipment for Wafer and Panel Level Packaging Revenue by Country (2021-2026) & (\$ millions)

Table 62. Europe Molding Equipment for Wafer and Panel Level Packaging Sales by Molding Method (2021-2026) & (Units)

Table 63. Europe Molding Equipment for Wafer and Panel Level Packaging Sales by Application (2021-2026) & (Units)

Table 64. Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales by Country (2021-2026) & (Units)

Table 65. Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Country (2021-2026)

Table 66. Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales by Molding Method (2021-2026) & (Units)

Table 67. Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales by Application (2021-2026) & (Units)

Table 68. Key Market Drivers & Growth Opportunities of Molding Equipment for Wafer and Panel Level Packaging

Table 69. Key Market Challenges & Risks of Molding Equipment for Wafer and Panel Level Packaging

Table 70. Key Industry Trends of Molding Equipment for Wafer and Panel Level Packaging

Table 71. Molding Equipment for Wafer and Panel Level Packaging Raw Material

Table 72. Key Suppliers of Raw Materials

Table 73. Molding Equipment for Wafer and Panel Level Packaging Distributors List

Table 74. Molding Equipment for Wafer and Panel Level Packaging Customer List

Table 75. Global Molding Equipment for Wafer and Panel Level Packaging Sales Forecast by Region (2027-2032) & (Units)

Table 76. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Forecast by Region (2027-2032) & (\$ millions)

Table 77. Americas Molding Equipment for Wafer and Panel Level Packaging Sales Forecast by Country (2027-2032) & (Units)

Table 78. Americas Molding Equipment for Wafer and Panel Level Packaging Annual Revenue Forecast by Country (2027-2032) & (\$ millions)

Table 79. APAC Molding Equipment for Wafer and Panel Level Packaging Sales Forecast by Region (2027-2032) & (Units)

Table 80. APAC Molding Equipment for Wafer and Panel Level Packaging Annual Revenue Forecast by Region (2027-2032) & (\$ millions)

Table 81. Europe Molding Equipment for Wafer and Panel Level Packaging Sales Forecast by Country (2027-2032) & (Units)

Table 82. Europe Molding Equipment for Wafer and Panel Level Packaging Revenue Forecast by Country (2027-2032) & (\$ millions)

Table 83. Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales Forecast by Country (2027-2032) & (Units)

Table 84. Middle East & Africa Molding Equipment for Wafer and Panel Level

Packaging Revenue Forecast by Country (2027-2032) & (\$ millions)

Table 85. Global Molding Equipment for Wafer and Panel Level Packaging Sales Forecast by Molding Method (2027-2032) & (Units)

Table 86. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Forecast by Molding Method (2027-2032) & (\$ millions)

Table 87. Global Molding Equipment for Wafer and Panel Level Packaging Sales Forecast by Application (2027-2032) & (Units)

Table 88. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Forecast by Application (2027-2032) & (\$ millions)

Table 89. Towa Basic Information, Molding Equipment for Wafer and Panel Level Packaging Manufacturing Base, Sales Area and Its Competitors

Table 90. Towa Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

Table 91. Towa Molding Equipment for Wafer and Panel Level Packaging Sales (Units), Revenue (\$ Million), Price (US\$/Unit) and Gross Margin (2021-2026)

Table 92. Towa Main Business

Table 93. Towa Latest Developments

Table 94. Besi Basic Information, Molding Equipment for Wafer and Panel Level Packaging Manufacturing Base, Sales Area and Its Competitors

Table 95. Besi Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

Table 96. Besi Molding Equipment for Wafer and Panel Level Packaging Sales (Units), Revenue (\$ Million), Price (US\$/Unit) and Gross Margin (2021-2026)

Table 97. Besi Main Business

Table 98. Besi Latest Developments

Table 99. ASMPT Basic Information, Molding Equipment for Wafer and Panel Level Packaging Manufacturing Base, Sales Area and Its Competitors

Table 100. ASMPT Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

Table 101. ASMPT Molding Equipment for Wafer and Panel Level Packaging Sales (Units), Revenue (\$ Million), Price (US\$/Unit) and Gross Margin (2021-2026)

Table 102. ASMPT Main Business

Table 103. ASMPT Latest Developments

Table 104. APIC YAMADA (Yamaha Robotics) Basic Information, Molding Equipment for Wafer and Panel Level Packaging Manufacturing Base, Sales Area and Its Competitors

Table 105. APIC YAMADA (Yamaha Robotics) Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

Table 106. APIC YAMADA (Yamaha Robotics) Molding Equipment for Wafer and Panel

Level Packaging Sales (Units), Revenue (\$ Million), Price (US\$/Unit) and Gross Margin (2021-2026)

Table 107. APIC YAMADA (Yamaha Robotics) Main Business

Table 108. APIC YAMADA (Yamaha Robotics) Latest Developments

Table 109. Shanghai Xinsheng Basic Information, Molding Equipment for Wafer and Panel Level Packaging Manufacturing Base, Sales Area and Its Competitors

Table 110. Shanghai Xinsheng Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

Table 111. Shanghai Xinsheng Molding Equipment for Wafer and Panel Level Packaging Sales (Units), Revenue (\$ Million), Price (US\$/Unit) and Gross Margin (2021-2026)

Table 112. Shanghai Xinsheng Main Business

Table 113. Shanghai Xinsheng Latest Developments

Table 114. Tongling Trinity Technology Basic Information, Molding Equipment for Wafer and Panel Level Packaging Manufacturing Base, Sales Area and Its Competitors

Table 115. Tongling Trinity Technology Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

Table 116. Tongling Trinity Technology Molding Equipment for Wafer and Panel Level Packaging Sales (Units), Revenue (\$ Million), Price (US\$/Unit) and Gross Margin (2021-2026)

Table 117. Tongling Trinity Technology Main Business

Table 118. Tongling Trinity Technology Latest Developments

Table 119. I-PEX Basic Information, Molding Equipment for Wafer and Panel Level Packaging Manufacturing Base, Sales Area and Its Competitors

Table 120. I-PEX Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

Table 121. I-PEX Molding Equipment for Wafer and Panel Level Packaging Sales (Units), Revenue (\$ Million), Price (US\$/Unit) and Gross Margin (2021-2026)

Table 122. I-PEX Main Business

Table 123. I-PEX Latest Developments

Table 124. Kitakami Techno Basic Information, Molding Equipment for Wafer and Panel Level Packaging Manufacturing Base, Sales Area and Its Competitors

Table 125. Kitakami Techno Molding Equipment for Wafer and Panel Level Packaging Product Portfolios and Specifications

Table 126. Kitakami Techno Molding Equipment for Wafer and Panel Level Packaging Sales (Units), Revenue (\$ Million), Price (US\$/Unit) and Gross Margin (2021-2026)

Table 127. Kitakami Techno Main Business

Table 128. Kitakami Techno Latest Developments

List Of Figures

LIST OF FIGURES

Figure 1. Picture of Molding Equipment for Wafer and Panel Level Packaging

Figure 2. Molding Equipment for Wafer and Panel Level Packaging Report Years Considered

Figure 3. Research Objectives

Figure 4. Research Methodology

Figure 5. Research Process and Data Source

Figure 6. Global Molding Equipment for Wafer and Panel Level Packaging Sales Growth Rate 2021-2032 (Units)

Figure 7. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Growth Rate 2021-2032 (\$ millions)

Figure 8. Molding Equipment for Wafer and Panel Level Packaging Sales by Geographic Region (2021, 2025 & 2032) & (\$ millions)

Figure 9. Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Country/Region (2025)

Figure 10. Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Country/Region (2021, 2025 & 2032)

Figure 11. Product Picture of Compression Molding

Figure 12. Product Picture of Transfer Molding

Figure 13. Product Picture of Injection Molding

Figure 14. Product Picture of Vacuum-Assisted Molding

Figure 15. Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Molding Method in 2026

Figure 16. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Molding Method (2021-2026)

Figure 17. Product Picture of Wafer-Level Molding (200 Mm / 300 Mm)

Figure 18. Product Picture of Panel-Level Molding (Large Panel / Fan-Out Panel)

Figure 19. Product Picture of Strip-Level Molding

Figure 20. Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Substrate Format in 2026

Figure 21. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Substrate Format (2021-2026)

Figure 22. Product Picture of Semi-Automatic Molding System

Figure 23. Product Picture of Fully Automatic Molding System

Figure 24. Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Automation Level in 2026

Figure 25. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Automation Level (2021-2026)

Figure 26. Molding Equipment for Wafer and Panel Level Packaging Consumed in Semiconductor Packaging

Figure 27. Global Molding Equipment for Wafer and Panel Level Packaging Market: Semiconductor Packaging (2021-2026) & (Units)

Figure 28. Molding Equipment for Wafer and Panel Level Packaging Consumed in Advanced Packaging For Mobile And Consumer Electronics

Figure 29. Global Molding Equipment for Wafer and Panel Level Packaging Market: Advanced Packaging For Mobile And Consumer Electronics (2021-2026) & (Units)

Figure 30. Molding Equipment for Wafer and Panel Level Packaging Consumed in Automotive And Industrial Electronics

Figure 31. Global Molding Equipment for Wafer and Panel Level Packaging Market: Automotive And Industrial Electronics (2021-2026) & (Units)

Figure 32. Molding Equipment for Wafer and Panel Level Packaging Consumed in High-Reliability And IoT Devices

Figure 33. Global Molding Equipment for Wafer and Panel Level Packaging Market: High-Reliability And IoT Devices (2021-2026) & (Units)

Figure 34. Global Molding Equipment for Wafer and Panel Level Packaging Sale Market Share by Application (2025)

Figure 35. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Application in 2026

Figure 36. Molding Equipment for Wafer and Panel Level Packaging Sales by Company in 2026 (Units)

Figure 37. Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Company in 2026

Figure 38. Molding Equipment for Wafer and Panel Level Packaging Revenue by Company in 2026 (\$ millions)

Figure 39. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Company in 2026

Figure 40. Global Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Geographic Region (2021-2026)

Figure 41. Global Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Geographic Region in 2026

Figure 42. Americas Molding Equipment for Wafer and Panel Level Packaging Sales 2021-2026 (Units)

Figure 43. Americas Molding Equipment for Wafer and Panel Level Packaging Revenue 2021-2026 (\$ millions)

Figure 44. APAC Molding Equipment for Wafer and Panel Level Packaging Sales

2021-2026 (Units)

Figure 45. APAC Molding Equipment for Wafer and Panel Level Packaging Revenue 2021-2026 (\$ millions)

Figure 46. Europe Molding Equipment for Wafer and Panel Level Packaging Sales 2021-2026 (Units)

Figure 47. Europe Molding Equipment for Wafer and Panel Level Packaging Revenue 2021-2026 (\$ millions)

Figure 48. Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales 2021-2026 (Units)

Figure 49. Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Revenue 2021-2026 (\$ millions)

Figure 50. Americas Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Country in 2026

Figure 51. Americas Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Country (2021-2026)

Figure 52. Americas Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Molding Method (2021-2026)

Figure 53. Americas Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Application (2021-2026)

Figure 54. United States Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 55. Canada Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 56. Mexico Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 57. Brazil Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 58. APAC Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Region in 2026

Figure 59. APAC Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Region (2021-2026)

Figure 60. APAC Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Molding Method (2021-2026)

Figure 61. APAC Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Application (2021-2026)

Figure 62. China Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 63. Japan Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 64. South Korea Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 65. Southeast Asia Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 66. India Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 67. Australia Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 68. China Taiwan Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 69. Europe Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Country in 2026

Figure 70. Europe Molding Equipment for Wafer and Panel Level Packaging Revenue Market Share by Country (2021-2026)

Figure 71. Europe Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Molding Method (2021-2026)

Figure 72. Europe Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Application (2021-2026)

Figure 73. Germany Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 74. France Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 75. UK Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 76. Italy Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 77. Russia Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 78. Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Country (2021-2026)

Figure 79. Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Molding Method (2021-2026)

Figure 80. Middle East & Africa Molding Equipment for Wafer and Panel Level Packaging Sales Market Share by Application (2021-2026)

Figure 81. Egypt Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 82. South Africa Molding Equipment for Wafer and Panel Level Packaging Revenue Growth 2021-2026 (\$ millions)

Figure 83. Israel Molding Equipment for Wafer and Panel Level Packaging Revenue

Growth 2021-2026 (\$ millions)

Figure 84. Turkey Molding Equipment for Wafer and Panel Level Packaging Revenue

Growth 2021-2026 (\$ millions)

Figure 85. GCC Countries Molding Equipment for Wafer and Panel Level Packaging

Revenue Growth 2021-2026 (\$ millions)

Figure 86. Manufacturing Cost Structure Analysis of Molding Equipment for Wafer and Panel Level Packaging in 2026

Figure 87. Manufacturing Process Analysis of Molding Equipment for Wafer and Panel Level Packaging

Figure 88. Industry Chain Structure of Molding Equipment for Wafer and Panel Level Packaging

Figure 89. Channels of Distribution

Figure 90. Global Molding Equipment for Wafer and Panel Level Packaging Sales

Market Forecast by Region (2027-2032)

Figure 91. Global Molding Equipment for Wafer and Panel Level Packaging Revenue

Market Share Forecast by Region (2027-2032)

Figure 92. Global Molding Equipment for Wafer and Panel Level Packaging Sales

Market Share Forecast by Molding Method (2027-2032)

Figure 93. Global Molding Equipment for Wafer and Panel Level Packaging Revenue

Market Share Forecast by Molding Method (2027-2032)

Figure 94. Global Molding Equipment for Wafer and Panel Level Packaging Sales

Market Share Forecast by Application (2027-2032)

Figure 95. Global Molding Equipment for Wafer and Panel Level Packaging Revenue

Market Share Forecast by Application (2027-2032)

I would like to order

Product name: Global Molding Equipment for Wafer and Panel Level Packaging Market Growth 2026-2032

Product link: <https://marketpublishers.com/r/GE37AC981205EN.html>

Price: US\$ 3,660.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/GE37AC981205EN.html>